L Number	Hits	Search Text	DB	Time stamp
1	68153	adhesive near bond$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/14 16:01
2	33405	induction near heating	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/14 16:02
3	192	susceptor near thickness	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/14 16:03
4	41659	eddy near current	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/14 16:03
5	118170	219/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/14 16:03
6	679	(adhesive near bond$) and (induction near heating)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/14 16:03
7	14	(susceptor near thickness) and ((adhesive near bond$) and (induction near heating))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/14 16:03
8	14	(eddy near current) and ((susceptor near thickness) and ((adhesive near bond$) and (induction near heating)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/14 16:03
9	8	219/$.ccls. and ((eddy near current) and ((susceptor near thickness) and ((adhesive near bond$) and (induction near heating))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/14 16:03